

## FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

<b>Title of Invention</b>	[MOLD AND METHOD OF MOLDING SEMICONDUCTOR DEVICES]					
Application Number :						
Date :						
First Named Applicant:		Mr. Jen-Chieh Kao				
Attorney Docket Number:		11184-US-PA				
<b>TOTAL FEE AUTHORIZED \$ 810</b>						
Patent fees are subject to annual revisions on or about October 1st of each year.						
Filing as large entity						
<b>BASIC FILING FEE</b>						
Fee Description		Fee Code	Amount \$	Fee Paid \$		
Utility Filing Fee		1001	770	770		
			Subtotal For Basic Filing Fees: \$ 770			
<b>EXTRA CLAIM FEES</b>						
Fee Description		Extra Claim	Fee Code	Amount \$	Fee Paid \$	
Total Claims : 19		0	1202	18	0	
Independent Claims : 3		0	1201	86	0	
			Subtotal For Extra Claims Fees: \$ 0			
<b>ASSIGNMENT FEES</b>						
Fee Description		Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee		00000000	1	8021	40	40
			Subtotal For Additional Fees: \$40			
<b>AUTHORIZED BILLING INFORMATION</b>						
<b>The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:</b>						
Credit account number:		1007				
Expiration Date (YYYYMMDD):		2005-12-31				
Authorized name:		YEH, WEN-HUNG				
Billing address:		99999				